


**• General Description**

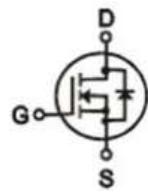
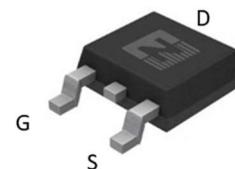
The ZM100N02D combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ . This device is ideal for load switch and battery protection applications.

**• Features**

- Advance high cell density Trench technology
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

**• Application**

- MB/VGA Vcore
- SMPS 2<sup>nd</sup> Synchronous Rectifier
- POL application
- BLDC Motor driver

**• Product Summary**

 $V_{DS} = 20V$ 
 $R_{DS(ON)} = 10m\Omega$ 
 $I_D = 25A$ 


TO-252

**• Ordering Information:**

Part NO.	ZM100N02D
Marking	ZM100N02
Packing Information	REEL TAPE
Basic ordering unit (pcs)	2500

**• Absolute Maximum Ratings ( $T_c = 25^\circ C$ )**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current	$I_D@T_c=25^\circ C$	25	A
	$I_D@T_c=75^\circ C$	19	A
	$I_D@T_c=100^\circ C$	15.8	A
Pulsed Drain Current <sup>①</sup>	$I_{DM}$	60	A
Total Power Dissipation( $T_c=25^\circ C$ )	$P_D@T_c=25^\circ C$	85	W
Total Power Dissipation( $T_A=25^\circ C$ )	$P_D@T_A=25^\circ C$	3.5	W
Operating Junction Temperature	$T_J$	-55 to 150	°C
Storage Temperature	$T_{STG}$	-55 to 150	°C
Single Pulse Avalanche Energy@ $L=0.1mH$	$E_{AS}$	50	mJ

**•Thermal resistance**

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	1.5	° C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	35	° C/W
Soldering temperature, wave soldering for 10s	T <sub>sold</sub>	-	-	265	° C

**•Electronic Characteristics**

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	20			V
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	0.5		1.2	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V			1.0	uA
Gate- Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V ,V <sub>DS</sub> =0V			±100	nA
Static Drain-source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A		10	13	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =8A		13	16	mΩ
Forward Trans conductance	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =10A		12		s
Source-drain voltage	V <sub>SD</sub>	I <sub>S</sub> =10A			1.28	V

**•Electronic Characteristics**

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V f=1MHZ	-	950	-	pF
Output capacitance	C <sub>oss</sub>		-	230	-	
Reverse transfer capacitance	C <sub>rss</sub>		-	100	-	

**•Gate Charge characteristics**

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q <sub>g</sub>	V <sub>DD</sub> =15V I <sub>D</sub> = 10A V <sub>GS</sub> = 4.5V	-	12	-	nC
Gate - Source charge	Q <sub>gs</sub>		-	4	-	
Gate - Drain charge	Q <sub>gd</sub>		-	6	-	

Note: ① Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% ;



Fig.1 Gate-Charge Characteristics

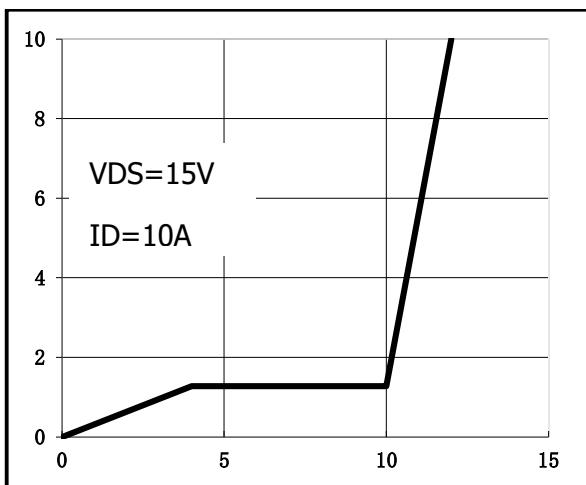


Fig.2 Capacitance Characteristics

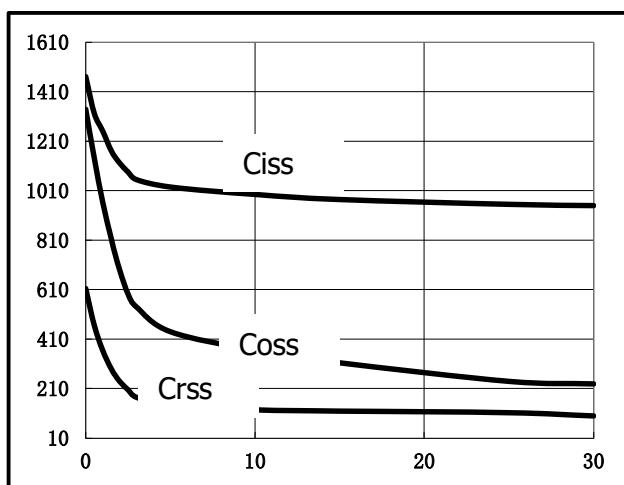


Fig.3 Power Dissipation Derating Curve

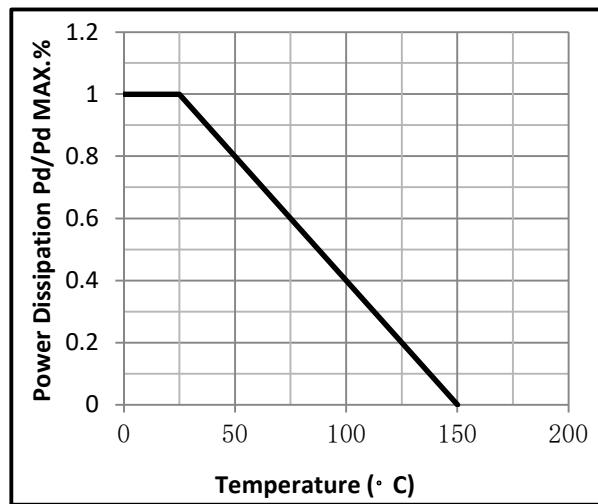


Fig.4 Typical output Characteristics

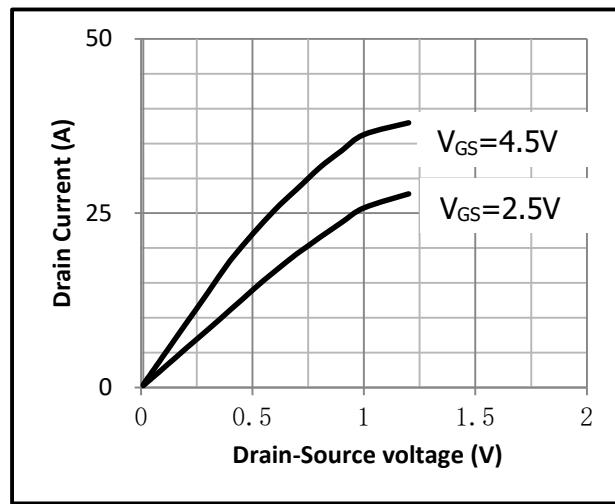


Fig.5 Threshold Voltage V.S Junction Temperature

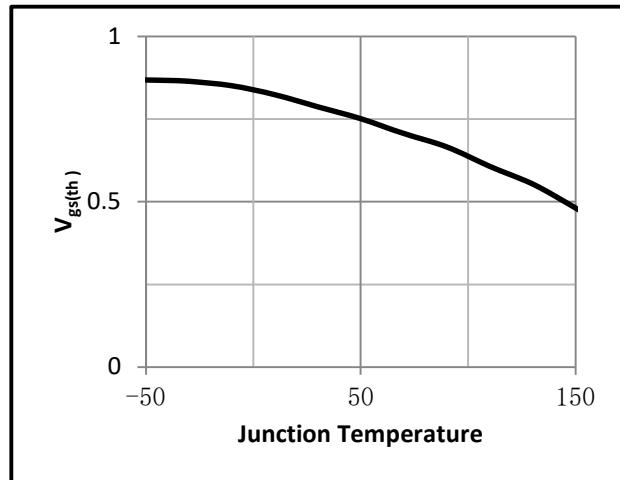


Fig.6 Resistance V.S Drain Current

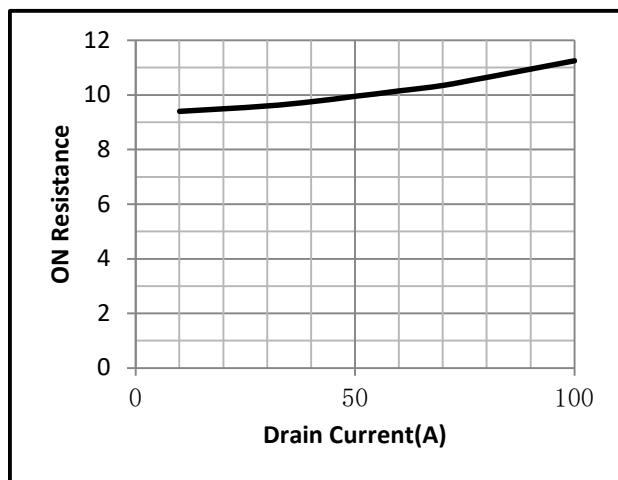




Fig.7 On-Resistance VS Gate Source Voltage

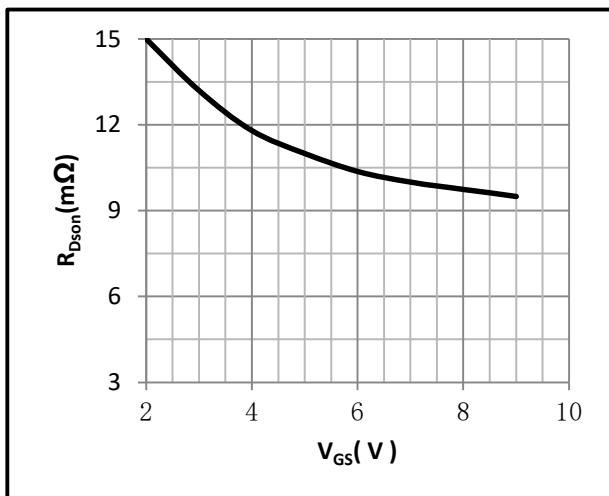


Fig.8 On-Resistance V.S Junction Temperature

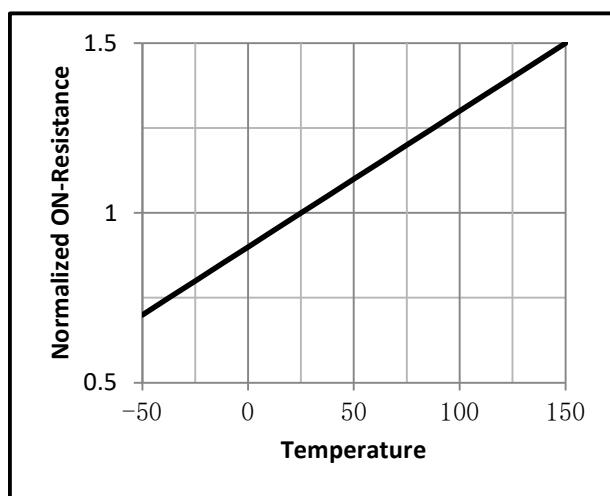


Fig.9 Switching Time Measurement Circuit

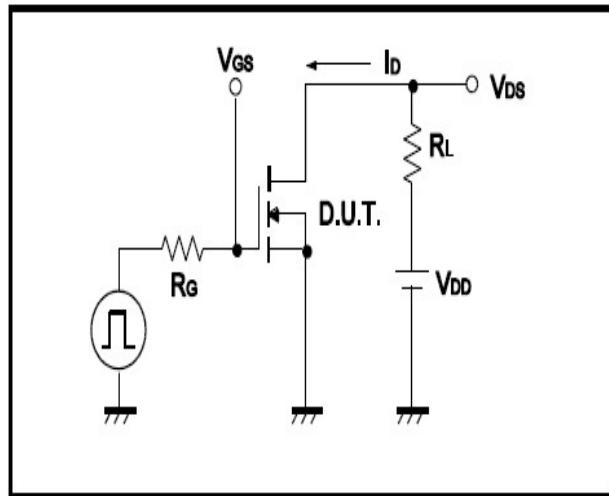


Fig.10 Switching Time Waveform

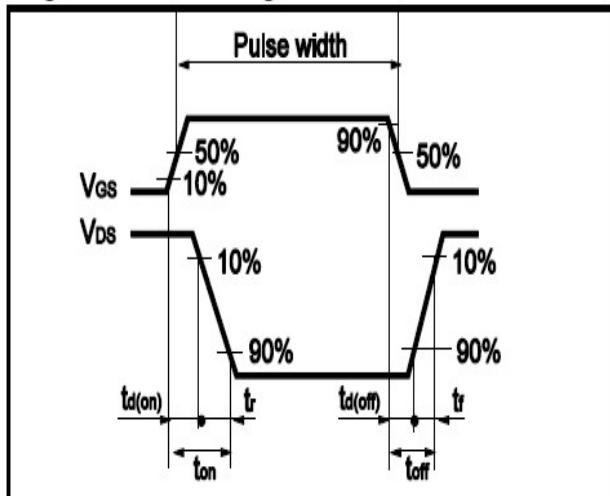


Fig.11 Avalanche Measurement Circuit

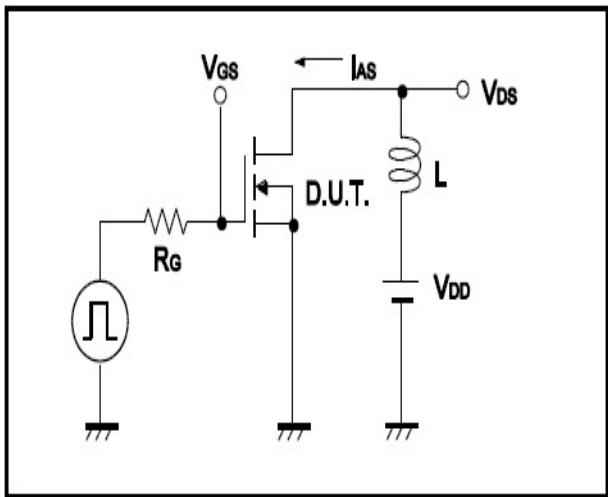
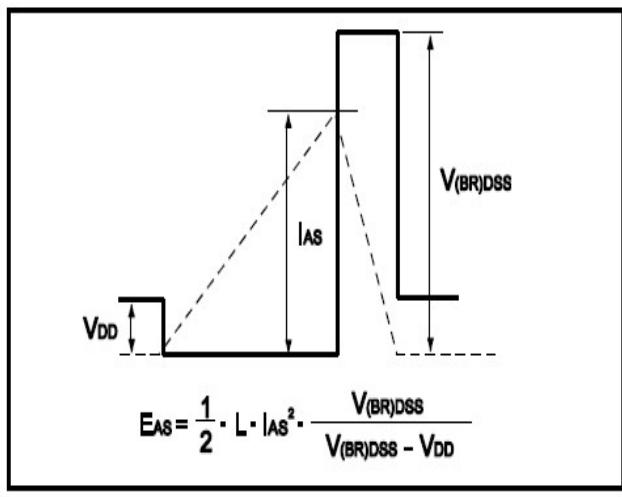


Fig.12 Avalanche Waveform





## •Dimensions (TO-252)

Unit: mm

SYMBOL	min	max	SYMBOL	min	max
A	2.10	2.50	B	0.85	1.25
b	0.50	0.80	b1	0.50	0.90
b2	0.45	0.70	C	0.45	0.70
D	6.30	6.75	D1	5.10	5.50
E	5.30	6.30	e1	2.25	2.35
L1	9.20	10.60	e2	4.45	4.75
L2	0.90	1.75	L3	0.60	1.10
K	0.00	0.23			

